

## **Product Bulletin**

Document # : PB21388Z Issue Date: 12 August 2016

Title of Change:	Datasheet update for the NCV7321, NCV7428 and NCV7342 ON Semiconductor products reflecting the update to the DFN8 package case.			
Effective Date:	12 August 2016			
Contact information:	Contact your local ON Semiconductor Sales Office or <liesje.vandenmeersschau@onsemi.com></liesje.vandenmeersschau@onsemi.com>			
Type of notification:	ON Semiconductor will consider this change accepted.			
Change category:	Wafer Fab Change	Assembly Change	☐ Test Change	
Change Sub-Category(s):  Manufacturing Site Change/ Manufacturing Process Change/		l Change specific change	<ul><li>☑ Datasheet/Product Doc change</li><li>☑ Shipping/Packaging/Marking</li><li>☑ Other:</li></ul>	
Sites Affected:  All site(s)  not ap	oplicable ON Sem	iconductor site(s) :	External Foundry/Subcon site(s)	
Description and Purpose:  Updating the DFN8 package case in the datasheet: CASE 506CS replaced by CASE 506DG  This is a format only change to improve readability to customers. There is no change to the physical package dimensions.				
List of affected Standard Parts	<b>5</b> :			
NCV7321D11R2G	NCV7428D13R2G	NCV7428MW3R2G	NCV7342D13R2G	
NCV7321D12R2G N	NCV7428D1L5R2G	NCV7428MWL5R2G	NCV7342MW3R2G	
NCV7321MW2R2G	ICV7428D1L3R2G	NCV7428MWL3R2G		
NCV7428D15R2G N	NCV7428MW5R2G	NCV7342D10R2G		

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